

D I C E N T R A S C H E M A T I C S

M a i n t e n a n c e P a n e l

Table of contents

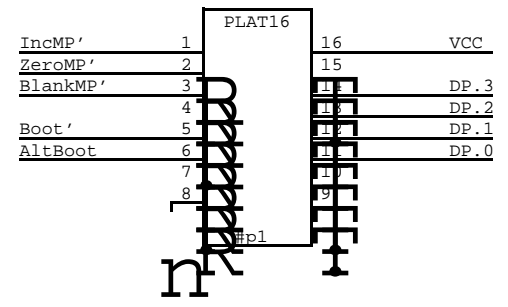
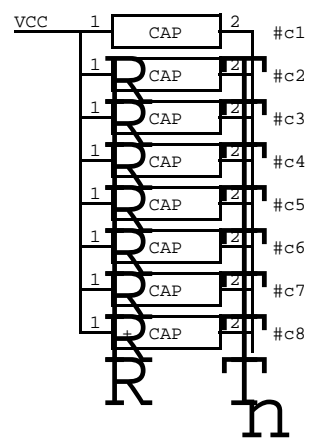
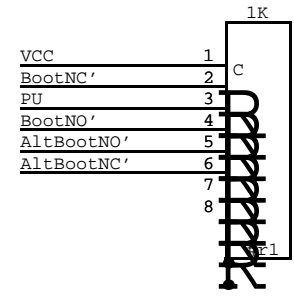
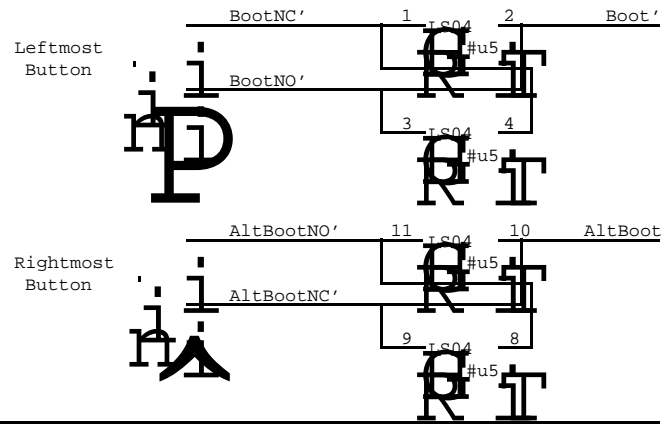
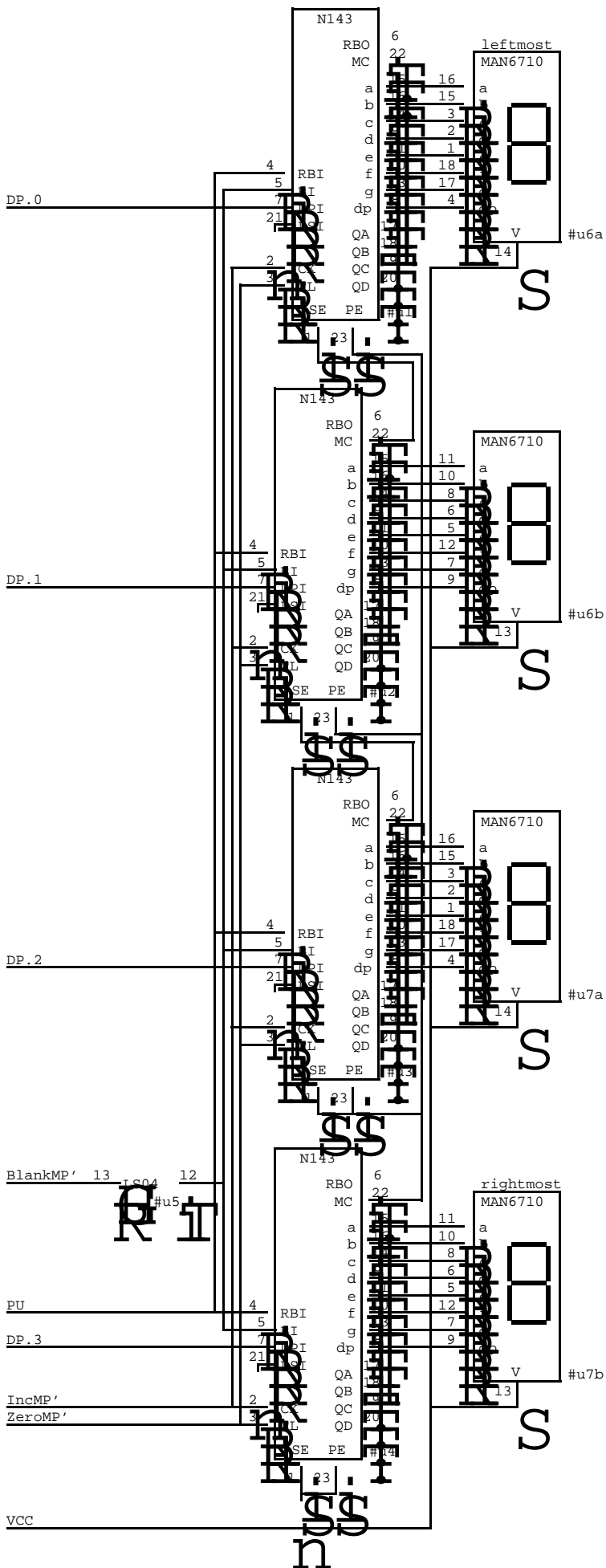
<u>TITLE</u>	<u>PAGE</u>
Maintenance Panel _____	1
MP-CP Cable _____	2
Parts List _____	3
Fabrication Drawing _____	4
Assembly Drawing _____	5

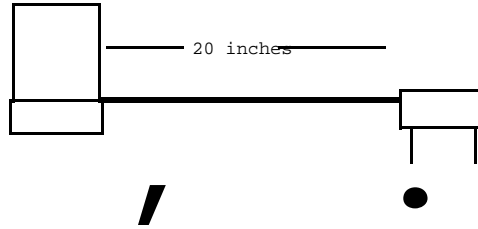
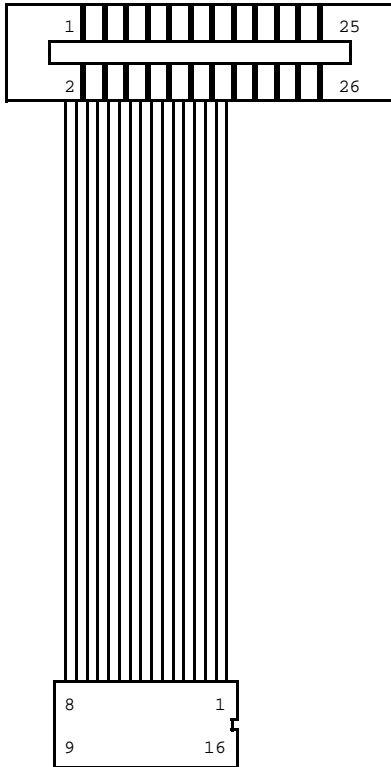
These drawings use the following [SIL] User.cm parameters:

- 0: Helvetica10
- 1: Helvetica7
- 2: Template64
- 3: Gates32
- 5: Dicentra.lb5
- 6: Dicentra.lb6
- 7: Dicentra.lb7
- 8: Dicentra.lb8
- A: Dicentra.Analyze
- Y: 712

All files are kept on [Indigo]<Dicentra>

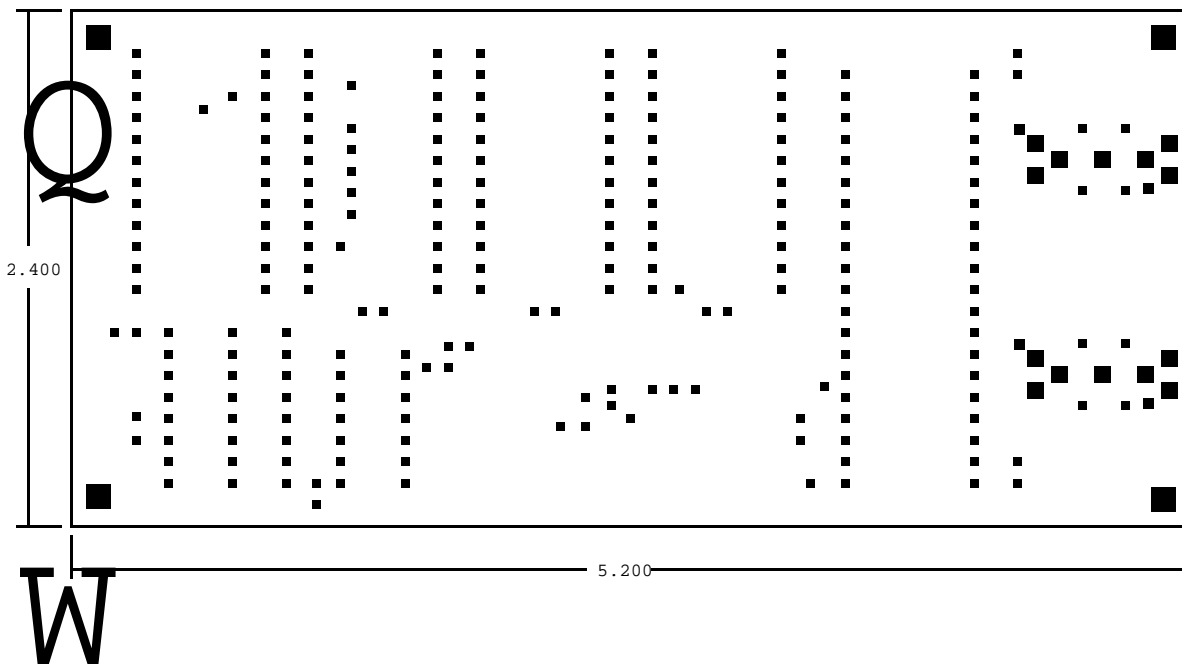
XEROX PARC	Project Dicentra	Reference Title Page	File 'DMP-Rev-0.sil	Designer David Boggs	Rev 0	Date 7/1/83	Page 0
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Signal Name	Edge Connector	DIP Connector
IncMP'	15	1
ZeroMP'	13	2
BlankMP'	11	3
Boot'	7	5
AltBoot	5	6
DP.3	12	14
DP.2	10	13
DP.1	8	12
DP.0	6	11
VCC	1	8
GND	16	16

Component side

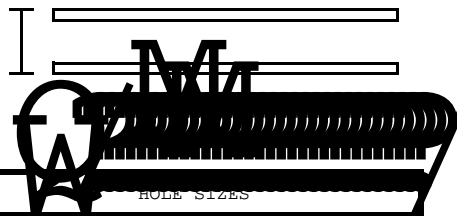


NOTES

All dimensions are in inches; drawing is not to scale.
 X.XXX is +/- .005; X.XX is +/- .010.
 Except as noted, this printed board shall be made
 in accordance with IPC-D-320.
 Acceptability of the finished board will be judged
 in accordance with IPC-A-600.
 Base Laminate: 1 oz Cu on FR4
 in accordance with IPC-L-130.
 Solder mask: green epoxy
 in accordance with IPC-SM-840.
 Silk screen: white epoxy.

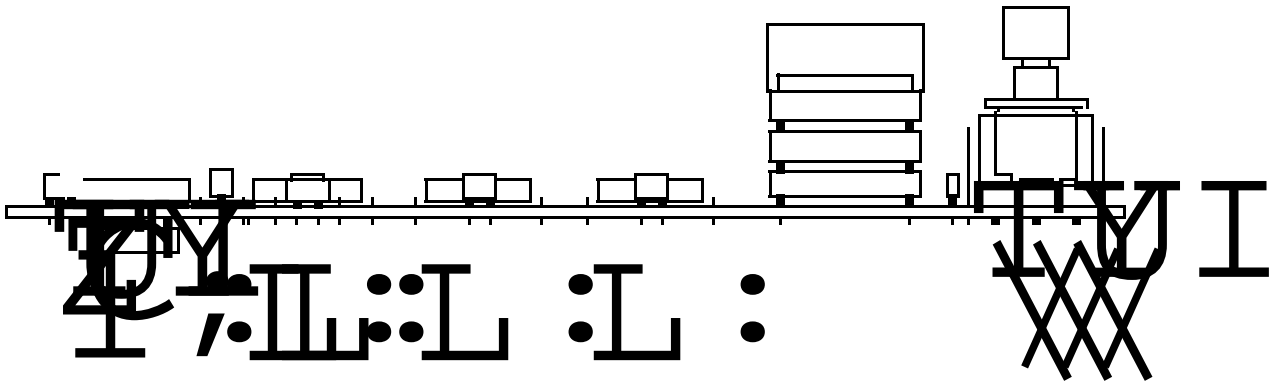
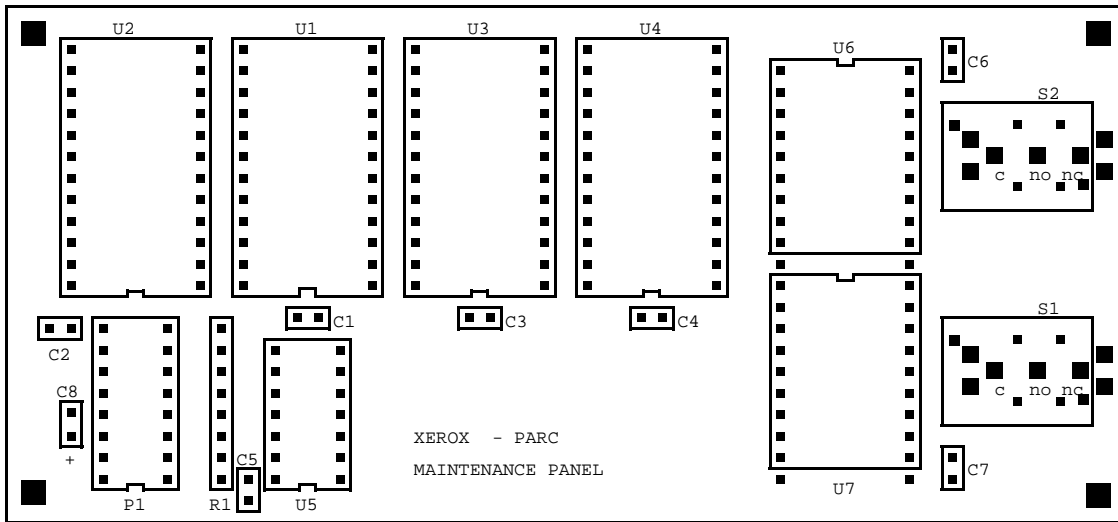
Copper plane
 Epoxy glass

.062



Symbol	Number	Size	Plated
■	4	.125	No
■	14	.075	Yes
■	4	.050	Yes
■	225	.031	Yes

Component side



XEROX PARC	Project Dicentra	Reference Assembly Drawing	File DMP05.sil	Designer David Boggs	Rev 0	Date 7/1/83	Page 5
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